L Number	Hits	Search Text	DB	Time stamp
10	2	(US-20020074381-\$).did.	USPAT;	2003/09/16 13:16
			US-PGPUB;	
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11	2	((US-20020074381-\$).did.) and (in or indium)	USPAT;	2003/09/16 12:52
		·	US-PGPUB;	
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12	14	(("6087021") or ("5812925") or ("4325734")	USPAT	2003/09/16 12:53
		or ("5621607") or ("3602979") or ("4614296")		
		or ("6520401") or ("6187450") or ("5392982")		
		or ("5542602") or ("6199751") or ("6340113")		
		or ("5009360") or ("5025304")).PN.		-
13	10	((("6087021") or ("5812925") or ("4325734")	USPAT;	2003/09/16 13:16
1.5	10	or ("5621607") or ("3602979") or ("4614296")	US-PGPUB;	2003/03/10 13:10
		or ("6520401") or ("6187450") or ("5392982")	EPO; JPO;	
		or ("5542602") or ("6199751") or ("6340113")	DERWENT;	
		or ("5009360") or ("5025304")).PN.) and	IBM TDB	
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14	10	optics or optical) (US-6340113-\$ or US-6199751-\$ or	110035	0000/00/16 10 55
14	10		USPAT	2003/09/16 12:55
		US-6087021-\$ or US-5812925-\$ or US-5621607-\$		
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15	9	, , ,	USPAT;	2003/09/16 13:23
i		US-6087021-\$ or US-5812925-\$ or US-5621607-\$	US-PGPUB;	
		or US-5542602-\$ or US-5392982-\$ or	EPO; JPO;	
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		US-4325734-\$).did.) and (below or lower or	IBM_TDB	
		less) with (melt or melting or liqu\$9) with		
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10	4	(US-5009360-\$ or US-5621607-\$ or US-5812925-\$ or US-4325734-\$).did.	USPAT	2003/09/16 13:03
17	1	((US-5009360-\$ or US-5621607-\$ or	TICDAM.	2002/00/16 12:16
	4		USPAT;	2003/09/16 13:16
		US-5812925-\$ or US-4325734-\$).did.) and (electronic or electronics or chip or chips	US-PGPUB;	
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18	1247	228/193-195.ccls.	HCDAT.	2002/00/16 12:16
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13	111		USPAT;	2003/09/16 13:22
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	İ	semiconductors or optic or optics or	DERWENT;	
20		optical) with (bond\$9 or join\$9)	IBM_TDB	0000/00/55 55 55
20	80	228/193-195.ccls. and (electronic or	USPAT;	2003/09/16 13:23
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		or solder\$9)		

21	119	(228/193-195.ccls. and (electronic or	USPAT:	2003/09/16 13:23
		electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (bond\$9 or join\$9)) or (228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (diffus\$9 or weld\$9 or braz\$9 or solder\$9))	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
22	64	((228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (bond\$9 or join\$9)) or (228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (diffus\$9 or weld\$9 or braz\$9 or solder\$9))) and (below or lower or less) with (melt or melting or liqu\$9) with (point or points or temperature or temperatures)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:23
23	119	((228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (bond\$9 or join\$9)) or (228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (diffus\$9 or weld\$9 or braz\$9 or solder\$9))) or (((228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (bond\$9 or join\$9)) or (228/193-195.ccls. and (electronic or electronics or chip or pcbs or circuit or circuits or semiconductor or semiconductor or semiconductor or semiconductor or optics or optical) with (diffus\$9 or weld\$9 or braz\$9 or solder\$9))) and (below or lower or less) with (melt or melting or liqu\$9) with (point or points or temperature or temperatures))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:24